

### MTD2955E-VB Datasheet

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)			
- 60	0.061 at V <sub>GS</sub> = - 10 V	- 30	10			
	0.072 at V <sub>GS</sub> = - 4.5 V	- 25	10			

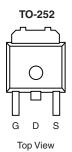
#### **FEATURES**

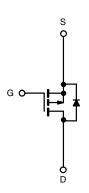
- Trench Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_C = 25$ °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T <sub>.I</sub> = 175 °C)	T <sub>C</sub> = 25 °C	I_	- 30			
Commudus Diam Guilent (1) = 173 O)	T <sub>C</sub> = 100 °C	I <sub>D</sub>	- 25			
Pulsed Drain Current	I <sub>DM</sub>	- 30	А			
Continuing Source Current (Diode Conduction)	I <sub>S</sub>	- 20				
Avalanche Current	I <sub>AS</sub>	- 20				
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ		
Maximum Daway Dissination	T <sub>C</sub> = 25 °C	В	34 <sup>a</sup>	w		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	4 <sup>b</sup>	l vv		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hunghian ta Ambianto	t ≤ 10 sec	R <sub>thJA</sub>	20	25	°C/W	
Junction-to-Ambient <sup>D</sup>	Steady State		62	75		
Junction-to-Case		R <sub>thJC</sub>	5	6		

#### Notes:

- a. See SOA curve for voltage derating.
- b. Surface Mounted on 1" x 1" FR-4 boad.

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Parameter	Symbol	Test Conditions	Min	Typ <sup>a</sup>	Max	Unit	
Static	1 -7			-71			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60		1 .,		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0	- 2.0	- 3.0	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μΑ	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 150		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 10			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A		0.061			
	_	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 125 °C		0.100			
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 175 °C		0.150		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2 A		0.072		1	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A		8		S	
Dynamic		· · · · · · · · · · · · · · · · · · ·		•			
Input Capacitance	C <sub>iss</sub>			1000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Gate Charge	$Q_g$			10		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8.4 \text{ A}$		2.1			
Gate-Drain Charge	$Q_{gd}$			3.2			
Gate Resistance	$R_g$	f = 1 MHz	8.0			Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			6			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, R_{L} = 3.57 \Omega$		15		- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ - 8.4 A, $V_{GEN} =$ - 10 V, $R_G = 2.5 \Omega$		16			
Fall Time <sup>c</sup>	t <sub>f</sub>	]		8			
Source-Drain Diode Ratings and Cha	racteristics	(T <sub>C</sub> = 25 °C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>				- 30	Α	
Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = - 2 A, V <sub>GS</sub> = 0 V		- 0.9	- 1.3	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 8 A, di/dt = 100 A/μs		50		ns	
Reverse Recovery Time	Q <sub>rr</sub>	- 1 <sub>F</sub> = - δ A, αι/αι = 100 A/μS		80		nC	

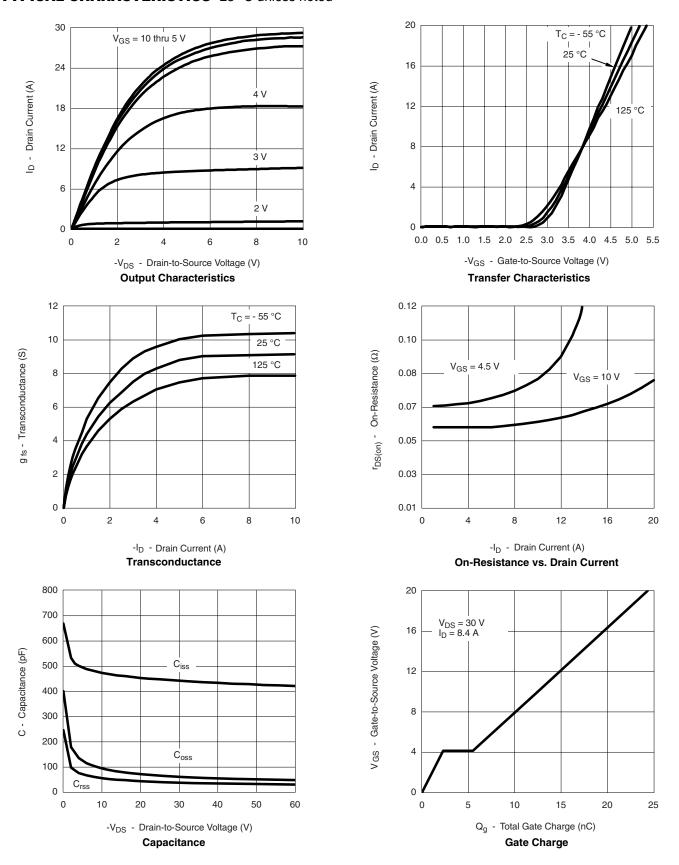
#### Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

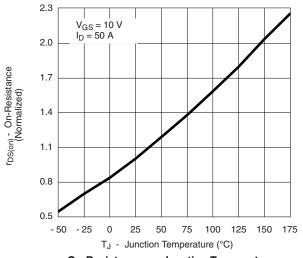


#### TYPICAL CHARACTERISTICS 25 °C unless noted

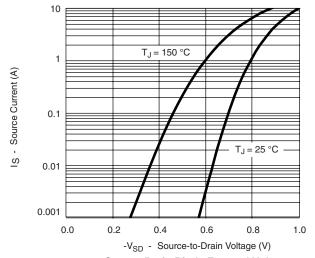




#### TYPICAL CHARACTERISTICS 25 °C unless noted



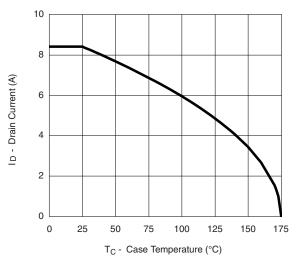
On-Resistance vs. Junction Temperature



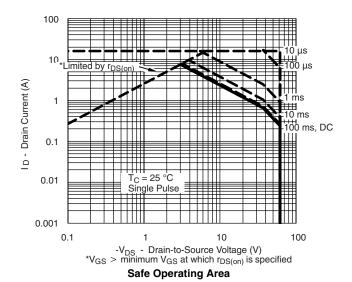
Source-Drain Diode Forward Voltage

#### THERMAL RATINGS

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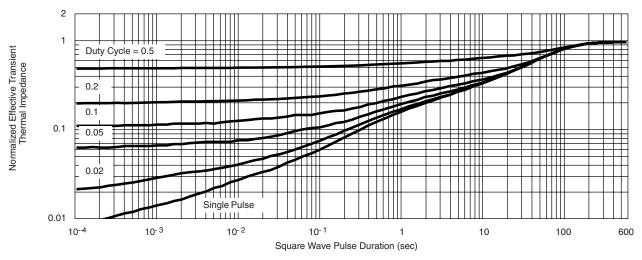
**Drain Current vs. Case Temperature** 



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#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Ambient

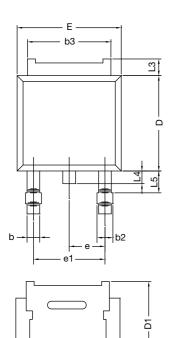


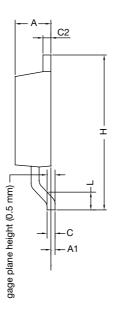
Normalized Thermal Transient Impedance, Junction-to-Case

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## **TO-252AA CASE OUTLINE**





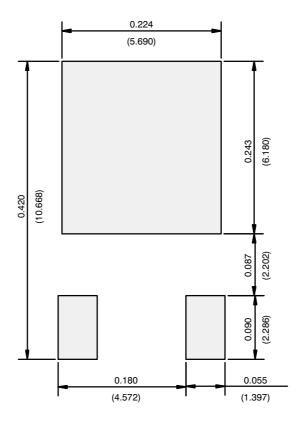
	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	1	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

#### Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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